



SPECIFICATION

- · Supplier : Samsung electro-mechanics
- · Product : Multi-layer Ceramic Capacitor
- · Samsung P/N:
- CL21B104KBCNNNC

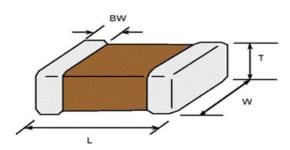
(Reference sheet)

- · Description :
- CAP, 100nF, 50V, ±10%, X7R, 0805

A. Samsung Part Number

		<u>CL</u> ①	<mark>21</mark> ②	<u>B</u> 3	<u>104</u> ④	<u>K</u> 5	<u>B</u> 6	<mark>C</mark> ⑦	<u>N</u> 8	<u>N</u> 9	<u>N</u> 10	<mark>C</mark> (1)		
1	Series	Samsung Multi-layer Ceramic Capacitor												
2	Size	0805 (inch coo	de)		L: :	2.00	± 0.10	mm			W:	1.25 ± 0.10	mm	
3	Dielectric	X7R				8	Inner	elect	rode			Ni		
4	Capacitance	100 nF					Term	inatio	on			Cu		
5	Capacitance	±10 %					Platir	ng				Sn 100%	(Pb Free)	
	tolerance					9	Prod	uct				Normal		
6	Rated Voltage	50 V				10	Spec	ial				Reserved for	r future use	
\bigcirc	Thickness	0.85 ± 0.10 mm				1	Pack	aging	I			Cardboard 1	ype, 7" reel	

B. Structure & Dimension



Samsung P/N	Dimension(mm)								
Samsung F/N	L	W	Т	BW					
CL21B104KBCNNNC	2.00 ± 0.10	1.25 ± 0.10	0.85 ± 0.10	0.50 +0.20/-0.30					

C. Samsung Reliablility Test and Judgement Condition

	Judgement	Test condition					
Capacitance	Within specified tolerance	1 ^{kHz} ±10% / 1.0±0.2Vrms					
Tan δ (DF)	0.025 max.	*A capacitor prior to measuring the capacitance is heat treated at 150°C+0/-10°C for 1 hour and maintained in ambient air for 24±2 hours.					
Insulation	10,000Mohm or 500Mohm× <i>µ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X7R						
Characteristics	(From-55℃ to 125℃, Capacitance change should be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·f, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
-	is to be soldered newly	245±5°C, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5°C, 10±1sec.					
Soldering Heat	Tan δ, IR : initial spec.						
Vibration Test	Capacitance change : within $\pm 5\%$ Tan δ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours × 3 direction (x, y, z)					
Moisture	Capacitance change : within ±12.5%	With rated voltage					
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs					
	IR : 500Mohm or 25Mohm × <i>μ</i> F Whichever is smaller						
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage					
Resistance	Tan δ : 0.05 max	Max. operating temperature					
	IR : 1,000Mohm or 50Mohm × <i>μ</i> F Whichever is smaller	1000+48/-0hrs					
Temperature	Capacitance change : within ±7.5%	1 cycle condition					
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25°C					
		→ Max. operating temperature → 25° C					
		E evelo test					
		5 cycle test					

X The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.